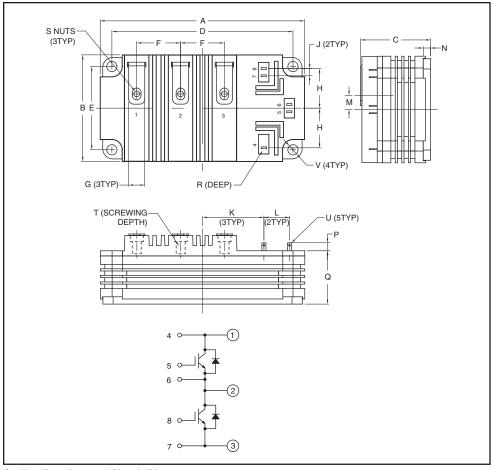


Dual IGBT HVIGBT Module 150 Amperes/4500 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
Α	5.51	140.0
В	2.87	73.0
С	1.89	48.0
D	4.88±0.01	124.0±0.25
E	2.24±0.01	57.0±0.25
F	1.18	30.0
G	0.43	11.0
Н	1.07	27.15
J	0.20	5.0
K	1.65	42.0

Dimensions	Inches	Millimeters
L	0.69±0.01	17.5±0.25
М	0.38	9.75
N	0.20	5.0
Р	0.22	5.5
Q	1.44	36.5
R	0.16	4.0
S	M6 Metric	M6
Т	0.63 Min.	16.0 Min.
U	0.11 x 0.02	2.8 x 0.5
V	0.28 Dia.	7.0 Dia.



Description:

Powerex HVIGBTs feature highly insulating housings that offer enhanced protection by means of greater creepage and strike clearance distance for many demanding applications like medium voltage drives and auxiliary traction applications.

Features:

- ☐ -40 to 150°C Extended Temperature Range
- ☐ 100% Dynamic Tested
- ☐ 100% Partial Discharge Tested
- ☐ Advanced Mitsubishi R-Series Chip Technology
- ☐ Aluminum Nitride (AIN) Ceramic Substrate for Low Thermal Impedance
- ☐ Complementary Line-up in Expanding Current Ranges to Mitsubishi HVIGBT Power Modules
- ☐ Copper Baseplate
- ☐ Creepage and Clearance Meet IEC 60077-1
- □ Rugged SWSOA and RRSOA

Applications:

- ☐ High Voltage Power Supplies
- ☐ Medium Voltage Drives
- ☐ Motor Drives
- ☐ Traction



QID4515002 **Dual IGBT HVIGBT Module** 150 Amperes/4500 Volts

Absolute Maximum Ratings, $T_i = 25$ °C unless otherwise specified

Ratings	Symbol	QID4515002	Units	
Junction Temperature	Tj	-40 to 150	°C	
Storage Temperature	T _{stg}	-40 to 125	°C	
Collector-Emitter Voltage ($V_{GE} = 0V$, $T_j = -40$ to $+125^{\circ}C$)	V _{CES}	4500	Volts	
Collector-Emitter Voltage ($V_{GE} = 0V, T_j = -50^{\circ}C$)	V _{CES}	4400	Volts	
Gate-Emitter Voltage (V _{CE} = 0V)	V _{GES}	±20	Volts	
Collector Current, DC (T _C = 82°C)	I _C	150	Amperes	
Peak Collector Current (Pulse)	I _{CM}	300 ^{*1}	Amperes	
Diode Forward Current*2	I _F	150	Amperes	
Diode Forward Surge Current (Pulse)*2	I _{FM}	300 ^{*1}	Amperes	
I^2 t for Diode (t = 10ms)	l ² t	10	kA ² sec	
Maximum Collector Dissipation (T _C = 25°C, IGBT Part, T _{j(max)} ≤ 150°C)	P _C	1500	Watts	
Mounting Torque, M6 Terminal Screws	_	44	in-lb	
Mounting Torque, M6 Mounting Screws	_	44	in-lb	
Module Weight (Typical)	_	900	Grams	
Isolation Voltage (Charged Part to Baseplate, AC 60Hz 1 min.)	V _{iso}	9.0	kVolts	
Partial Discharge	Q _{pd}	10	рС	
$(V1 = 4800 V_{RMS}, V2 = 3500 V_{RMS}, f = 60Hz (Acc. to IEC 1287))$	•			
Maximum Short-Circuit Pulse Width,	t _{psc}	10	μs	
$(V_{CC} \le 3200V, V_{GE} = \pm 15V, R_{G(off)} \ge 60\Omega, T_j = 125^{\circ}C)$	•			

Electrical Characteristics, $T_j = 25$ °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I _{CES}	$V_{CE} = V_{CES}, V_{GE} = 0V$	_	_	1.8	mA
Gate Leakage Current	I _{GES}	$V_{GE} = V_{GES}, V_{CE} = 0V$	_	_	0.5	μΑ
Gate-Emitter Threshold Voltage	V _{GE(th)}	I _C = 13.3mA, V _{CE} = 10V	5.8	6.3	6.8	Volts
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _C = 150A, V _{GE} = 15V, T _j = 25°C	_	3.8	_	Volts
		$I_C = 150A$, $V_{GE} = 15V$, $T_j = 125$ °C	_	4.6	5.5	Volts
Total Gate Charge	Q _G	V _{CC} = 2800V, I _C = 150A, V _{GE} = 15V	_	1.5	_	μC
Emitter-Collector Voltage*2	V _{EC}	$I_E = 150A$, $V_{GE} = 0V$, $T_j = 25$ °C	_	2.8	_	Volts
		$I_E = 150A$, $V_{GE} = 0V$, $T_j = 125$ °C	_	3.2	3.8	Volts

 ^{*1} Pulse width and repetition rate should be such that device junction temperature (T_j) does not exceed T_{j(max)} rating.
 *2 Represents characteristics od rhw anti-parallel, emitter-to-collector free-wheel diode (FWDi).



QID4515002 **Dual IGBT HVIGBT Module** 150 Amperes/4500 Volts

Electrical Characteristics, $T_i = 25$ °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Input Capacitance	C _{ies}		_	19	_	nF
Output Capacitance	C _{oes}	$V_{GE} = 0V, V_{CE} = 10V, f = 100kHz$	_	1.22	_	nF
Reverse Transfer Capacitance	C _{res}		_	0.55	_	nF
Turn-on Delay Time	t _{d(on)}	V _{CC} = 2800V, I _C = 133A,	_	1.00	_	μs
Rise Time	t _r	$V_{GE} = \pm 15V, R_{G(on)} = 24.3\Omega,$	_	0.30	_	μs
Turn-off Delay Time	t _{d(off)}	$R_{G(off)} = 90Ω$, $L_{S} = 150$ nH	_	3.6	_	μs
Fall Time	t _f	Inductive Load	_	0.36	_	μs
Turn-on Switching Energy	E _{on}	$T_j = 125$ °C, $I_C = 133$ A, $V_{GE} = \pm 15$ V,	_	0.55	_	J/P
Turn-off Switching Energy	E _{off}	$R_{G(on)} = 24.3\Omega, R_{G(off)} = 90\Omega,$	_	0.34	_	J/P
		V_{CC} = 2800V, L_S = 150nH , Inductive Load				
Diode Reverse Recovery Time*2	t _{rr}	V _{CC} = 2800V, I _E = 133A,	_	0.7	_	μs
Diode Reverse Recovery Charge*2	Q _{rr}	$V_{GE} = \pm 15V, R_{G(on)} = 24.3\Omega,$	_	111* ¹	_	μC
Diode Reverse Recovery Energy	E _{rec}	L _S = 150nH, Inductive Load	_	172	_	mJ/P
Stray Inductance (C1-E2)	L _{SCE}		_	60	_	nH
Lead Resistance Terminal-Chip	R _{CE}		_	0.8	_	mΩ

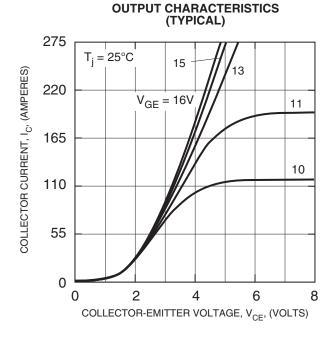
Thermal and Mechanical Characteristics, $T_j = 25$ °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case*3	R _{th(j-c)} Q	Per IGBT	_	_	0.083	°K/W
Thermal Resistance, Junction to Case*3	R _{th(j-c)} D	Per FWDi	_	_	0.157	°K/W
Contact Thermal Resistance, Case to Fin	R _{th(c-f)}	Per Module,	_	0.018	_	°K/W
		Thermal Grease Applied, $\lambda_{grease} = 1W/mK$				
Comparative Tracking Index	CTI		600	_	_	
Clearance Distance in Air (Terminal to Base)	d _{a(t-b)}		35.0	_	_	mm
Creepage Distance Along Surface	d _{s(t-b)}		64	_	_	mm
(Terminal to Base)						
Clearance Distance in Air	d _{a(t-t)}		19	_	_	mm
(Terminal to Terminal)						
Creepage Distance Along Surface	d _{s(t-t)}		54	_	_	mm
(Terminal to Terminal)						

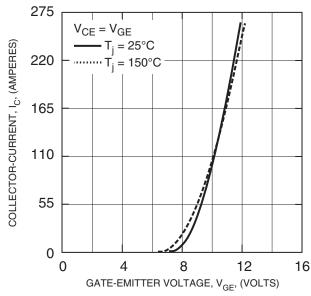
 ^{*1} Pulse width and repetition rate should be such that device junction temperature rise is negligible.
 *2 Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).
 *3 T_C measurement point is just under the chips.



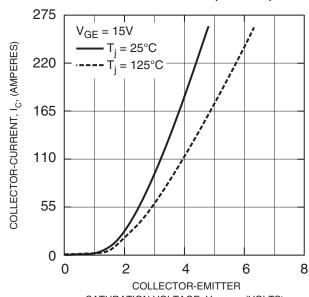
QID4515002 Dual IGBT HVIGBT Module 150 Amperes/4500 Volts



TRANSFER CHARACTERISTICS (TYPICAL)

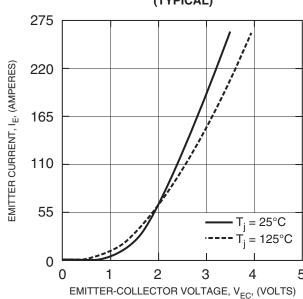


COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



SATURATION VOLTAGE, V_{CE(sat)}, (VOLTS)

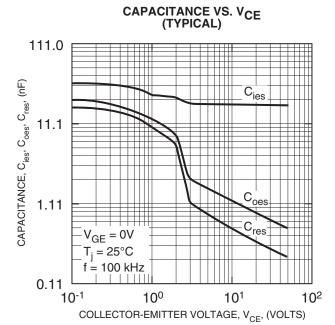
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



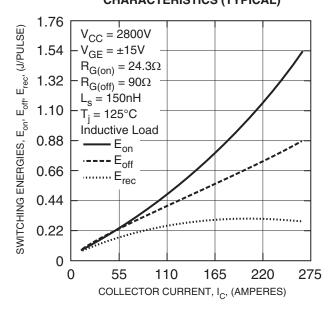


QID4515002 Dual IGBT HVIGBT Module

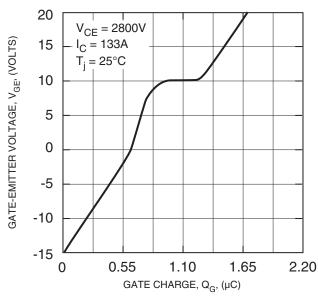
150 Amperes/4500 Volts



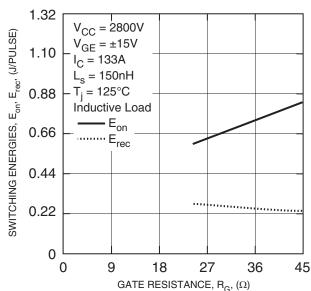
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



GATE CHARGE VS. VGE



HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)

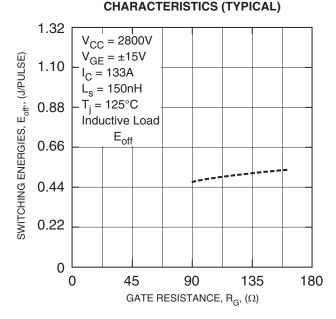




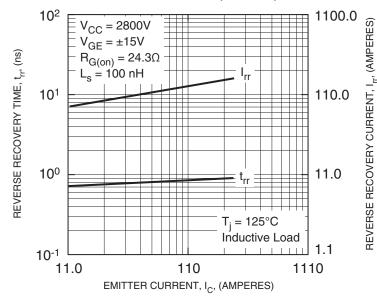
QID4515002 Dual IGBT HVIGBT Module 150 Amperes/4500 Volts

HALF-BRIDGE

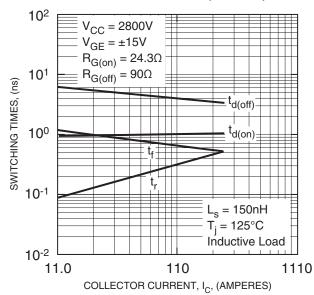
SWITCHING ENERGY



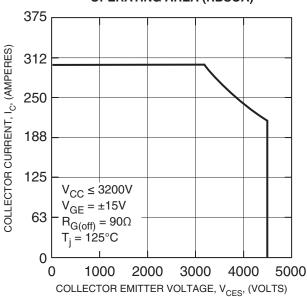
FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



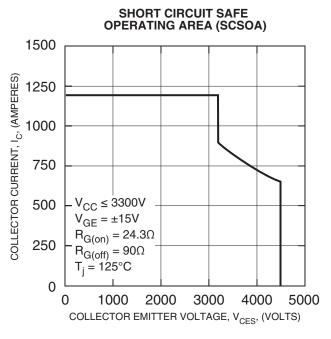
REVERSE BIAS SAFE OPERATING AREA (RBSOA)





QID4515002 Dual IGBT HVIGBT Module 150 Amperes/4500 Volts

oo yanga tak



REVERSE RECOVERY SAFE OPERATING AREA (RRSOA) 375 $V_{CC} \leq 3200V \\ di/dt < 660A/\mu s \\ T_{j} = 125^{\circ}C$ 188 125 63 63

2000

3000

EMITTER-COLLECTOR VOLTAGE, V_{EC} , (VOLTS)

4000

5000

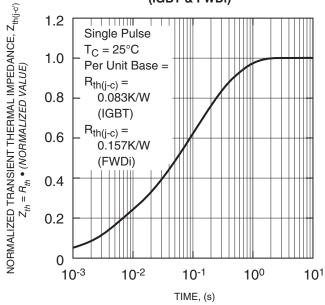
0

0

1000

FREE-WHEEL DIODE

TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT & FWDi)



11/14 Rev. 11